Amendments to the Specification:

Please replace paragraph [0031] with the following amended paragraph:

[0031] The clamp mechanism 34 of the present invention facilitates the pre-assembly, deployment, and retrieval of the array 20. The clamp mechanism 34 is capable of coupling to the tubing 14 and is capable of actively coupling the sensors of the sensor mechanism 32 to the inner wall of the casing 12. As will be evident herein, the clamp mechanism [[32]] 34 reduces or eliminates problems set forth above. Namely, use of the clamp mechanism [[32]] 34 may not significantly disrupt production from the well. Furthermore, preparing the clamp mechanisms [[32]] 34 for insertion into the well 10, properly coupling the sensor mechanisms 32 to the casing 12, and retrieving the sensors and clamp mechanisms 32 and 34 may not require tedious preparation and execution.

Please replace paragraph [0032] with the following amended paragraph:

[0032] Referring to Figures 2-3, a clamp mechanism 50 and a sensor mechanism 200 according to the present invention are schematically illustrated. As shown in Figure 2, the clamp mechanism 50 includes a body 60, an attachment device 70, mounting members 90, and a carrier mechanism 100. The clamp mechanism 50 also includes a biasing mechanism[[s]] 130, a guiding mechanism 140, and a release mechanism 150.

Please replace paragraph [0040] with the following amended paragraph:

[0040] Although the present embodiment of the clamp mechanism 50 is used with the multiple component sensor mechanism 200 having cylindrical housings, one skilled in the [[are]] art will appreciate that the clamp mechanism 50 can be used with other sensor mechanisms having other configurations. Accordingly, the channel 80 defined in the clamp mechanism 50 of Figure 2 can have rectilinear or other shapes. Furthermore, it is understood that the sensor mechanism 200 preferably has temperature, pressure, shock, and random vibration ratings suitable for deployment in a well. Consequently, the sensor mechanism 200 incorporated herein is suitable.

Please replace paragraph [0044] with the following amended paragraph:

[0044] A preferred method for interventionless activation of the release mechanism 150 uses the absolute pressure of the well to effectuate release of the carrier mechanism 100 with the mounted sensor component 250. As best described below with reference to Figures 9A-D, the release mechanism 150 in a preferred embodiment includes a rupture disc, which eliminates the need for a separate hydraulic, electrical, or telemetry system to activate the mechanism 150.

Please replace paragraph [0076] with the following amended paragraph:

[0076] Referring to Figure 8, a graph illustrates a first curve 146 of displacement versus load for an exemplary O-ring. Also illustrated on the graph is a second curve 147 of local stiffness versus load. The exemplary O-ring has an inner diameter of approximately 8-mm and a thickness of approximately 3-mm. As evidenced by the graph, the displacement versus load curve 146 is not a linear relationship. On the other hand, the "local stiffness" increases with the total load in an almost linear as shown by curve 147. As evidenced by the slope of line 148, which represents a "best fit" line of line 147, the graph shows that the effective "spring constant" of an O-ring squeezed between [[to]] two flat surfaces can be approximately 21-N/mm, which is the slope of line 148.

Please replace paragraph [0081] with the following amended paragraph:

[0081] In Figures 9A and 9C, the portions of the clamp mechanism include first and second sides members 88a-b and first and second supports 110a-b. The second side member 88b and the first and second supports 110a-b are shown in cross-section to[[.]] reveal internal components of the release mechanism 150. As best described above, the first and second side members 88a-b attach to the body 60 of the clamp mechanism with the sensor component (not shown) positioned therebetween. As also described above, the first and second supports 110a-b position adjacent the body 60 of the clamp mechanism and are used to support ends of the sensor component. The supports

110a-b define bores 119 for the springs 130a-b, guide holes 142 for the guide pins (not shown), and holes 116 for attaching to the carrier brackets (not shown).

Please replace paragraph [0100] with the following amended paragraph:

[0100] Referring to Figure 10B, the clamp mechanism 50 is lowered to a predetermined depth within the annulus 16. Hydrostatic pressure in the annulus 16, indicative [[or]] <u>of</u> a particular depth, triggers the release mechanism on the clamp 50 as described in detail above. The biasing mechanisms (not visible) disposed between the body 60 and the carrier mechanisms 100a-b move the carrier mechanisms 100a-b with mounted sensor component 250 approximately 10 to 15-mm towards the casing 12 to make contact with and to acoustically couple to the casing 12. Once acoustically coupled to the casing 12, the carrier mechanisms 100a-b can be used to transfer seismic signals from the casing 12 to the sensor component 250 mounted therein.